Celanese
The chemistry inside innovation™

HOSTAFORM® C 9021 S1

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POM copolymer Injection molding type with high rigidity, hardness and toughness; good chemical resistance. With tribological modification for demanding applications that require prevention of audible noise caused by stick-slip phenomenon. Available in natural and colored. Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470 Burning rate ISO 3795 and FMVSS 302 < 100mm/min for a thickness more than 1 mm. Ranges of applications: precision engineering, electric and electronical industry, domestic appliances. FDA = Food and Drug Administration (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	8.1	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2700	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	60	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	11.5	%	ISO 527-1/-2
Nominal strain at break	35	%	ISO 527-1/-2
Charpy impact strength, 23°C	180[P]	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	160	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	6	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.38[C]		

[P]: Partial Break

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Effective thermal diffusivity, flow	4.85E-8	m^2/s	ISO 22007-4
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low wear / Low friction

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

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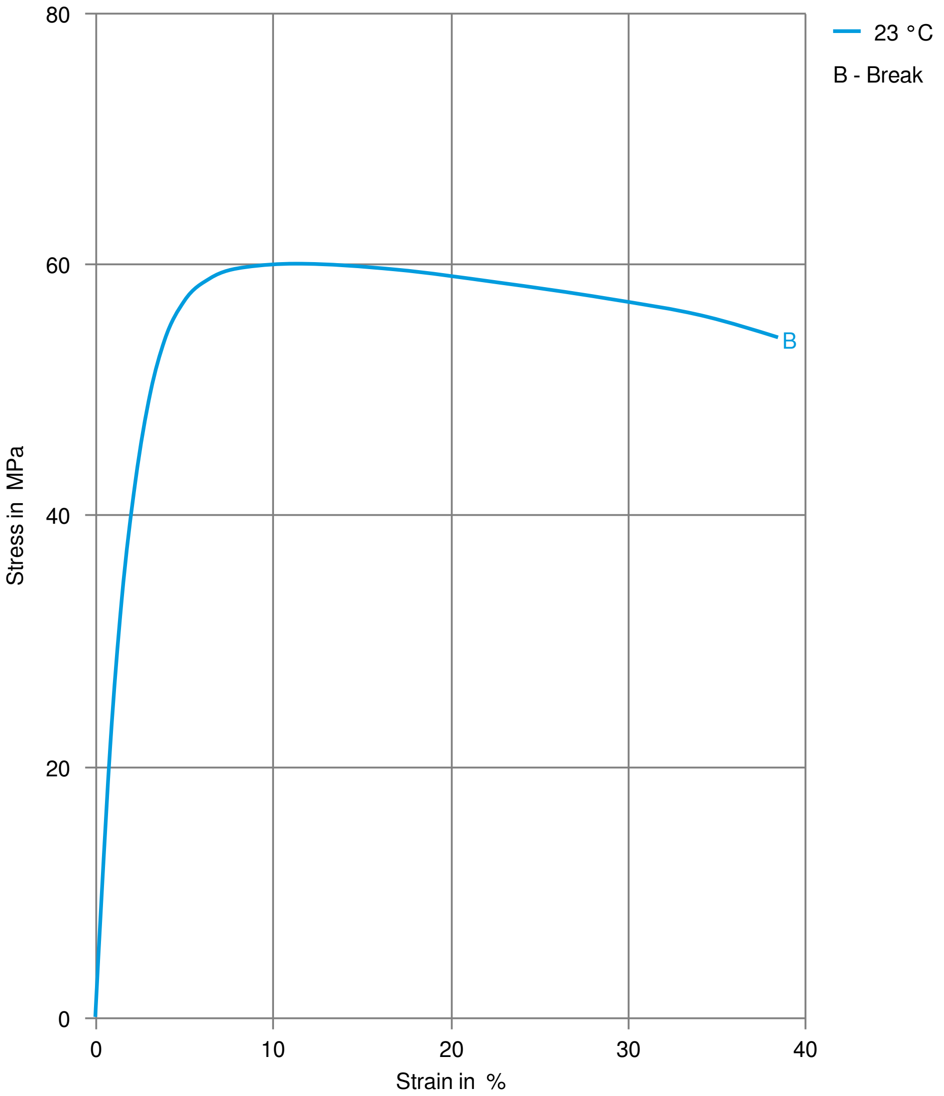
Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

Stress-strain



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Secant modulus-strain